



**THE DATASHEET OF
FDD3860**





ON Semiconductor®

FDD3860

N-Channel PowerTrench® MOSFET 100 V, 29 A, 36 mΩ

Features

- Max $r_{DS(on)}$ = 36 mΩ at $V_{GS} = 10$ V, $I_D = 5.9$ A
- High Performance Trench Technology for Extremely Low $r_{DS(on)}$
- 100% UIL Tested
- RoHS Compliant

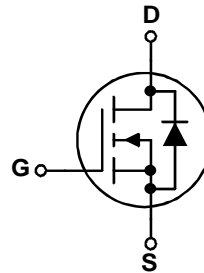
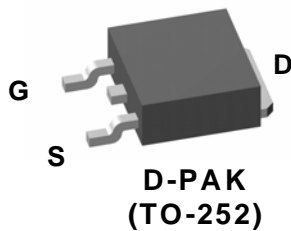


General Description

This N-Channel MOSFET is rugged gate version of ON Semiconductor's advanced Power Trench® process. This part is tailored for low $r_{DS(on)}$ and low Qg figure of merit, with avalanche ruggedness for a wide range of switching applications.

Applications

- DC-AC Conversion
- Synchronous Rectifier



MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted.

| Symbol | Parameter | Ratings | Units |
|----------------|--|------------------------------------|------------------|
| V_{DS} | Drain to Source Voltage | 100 | V |
| V_{GS} | Gate to Source Voltage | ± 20 | V |
| I_D | Drain Current -Continuous | $T_C = 25^\circ\text{C}$ | A |
| | -Continuous | $T_A = 25^\circ\text{C}$ (Note 1a) | |
| | -Pulsed | | |
| E_{AS} | Single Pulse Avalanche Energy | (Note 3) | mJ |
| P_D | Power Dissipation | $T_C = 25^\circ\text{C}$ | W |
| | Power Dissipation | $T_A = 25^\circ\text{C}$ (Note 1a) | |
| T_J, T_{STG} | Operating and Storage Junction Temperature Range | -55 to +175 | $^\circ\text{C}$ |

Thermal Characteristics

| | | | |
|-----------------|---|-----|--------------------|
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case | 1.8 | $^\circ\text{C/W}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | 40 | |

Package Marking and Ordering Information

| Device Marking | Device | Package | Reel Size | Tape Width | Quantity |
|----------------|---------|----------------|-----------|------------|------------|
| FDD3860 | FDD3860 | D-PAK (TO-252) | 13" | 16 mm | 2500 units |

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted.

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Units |
|--------|-----------|-----------------|------|------|------|-------|
|--------|-----------|-----------------|------|------|------|-------|

Off Characteristics

| | | | | | | |
|--------------------------------------|---|---|-----|----|-----------|----------------------|
| BV_{DSS} | Drain to Source Breakdown Voltage | $I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$ | 100 | | | V |
| $\frac{\Delta BV_{DSS}}{\Delta T_J}$ | Breakdown Voltage Temperature Coefficient | $I_D = 250\mu\text{A}$, referenced to 25°C | | 98 | | mV/ $^\circ\text{C}$ |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 80\text{V}, V_{GS} = 0\text{V}$ | | | 1 | μA |
| I_{GSS} | Gate to Source Leakage Current | $V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$ | | | ± 100 | nA |

On Characteristics

| | | | | | | |
|--|--|---|-----|-------|-----|----------------------|
| $V_{GS(th)}$ | Gate to Source Threshold Voltage | $V_{GS} = V_{DS}, I_D = 250\mu\text{A}$ | 2.5 | 3.8 | 4.5 | V |
| $\frac{\Delta V_{GS(th)}}{\Delta T_J}$ | Gate to Source Threshold Voltage Temperature Coefficient | $I_D = 250\mu\text{A}$, referenced to 25°C | | -11.4 | | mV/ $^\circ\text{C}$ |
| $r_{DS(on)}$ | Static Drain to Source On Resistance | $V_{GS} = 10\text{V}, I_D = 5.9\text{A}$ | | 29 | 36 | m Ω |
| | | $V_{GS} = 10\text{V}, I_D = 5.9\text{A}, T_J = 125^\circ\text{C}$ | | 51 | 64 | |
| g_{FS} | Forward Transconductance | $V_{DS} = 10\text{V}, I_D = 5.9\text{A}$ | | 20 | | S |

Dynamic Characteristics

| | | | | | | |
|------------|------------------------------|--|--|------|------|----------|
| C_{iss} | Input Capacitance | $V_{DS} = 50\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$ | | 1310 | 1740 | pF |
| C_{oss} | Output Capacitance | | | 100 | 130 | pF |
| C_{riss} | Reverse Transfer Capacitance | | | 45 | 70 | pF |
| R_g | Gate Resistance | $f = 1\text{MHz}$ | | 1.6 | | Ω |

Switching Characteristics

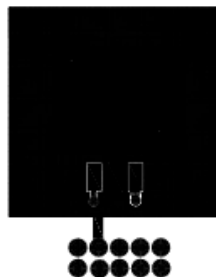
| | | | | | | |
|--------------|-------------------------------|--|--|-----|----|----|
| $t_{d(on)}$ | Turn-On Delay Time | $V_{DD} = 50\text{V}, I_D = 5.9\text{A}, V_{GS} = 10\text{V}, R_{GEN} = 6\Omega$ | | 16 | 29 | ns |
| t_r | Rise Time | | | 10 | 21 | ns |
| $t_{d(off)}$ | Turn-Off Delay Time | | | 24 | 39 | ns |
| t_f | Fall Time | | | 7 | 15 | ns |
| Q_g | Total Gate Charge at 10V | | $V_{DD} = 50\text{V}, I_D = 5.9\text{A}$ | | 22 | 31 |
| Q_{gs} | Gate to Source Charge | | | 7.1 | | nC |
| Q_{gd} | Gate to Drain "Miller" Charge | | | 6.3 | | nC |

Drain-Source Diode Characteristics

| | | | | | | |
|----------|---------------------------------------|--|--|-----|-----|----|
| V_{SD} | Source to Drain Diode Forward Voltage | $V_{GS} = 0\text{V}, I_S = 2.0\text{A}$ (Note 2) | | 0.7 | 1.2 | V |
| | | $V_{GS} = 0\text{V}, I_S = 5.9\text{A}$ (Note 2) | | 0.8 | 1.3 | |
| t_{rr} | Reverse Recovery Time | $I_F = 5.9\text{A}, di/dt = 100\text{A}/\mu\text{s}$ | | 34 | 55 | ns |
| Q_{rr} | Reverse Recovery Charge | | | 40 | 64 | nC |

Notes:

- 1: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.



a) $40^\circ\text{C}/\text{W}$ when mounted on a 1 in^2 pad of 2 oz copper



b) $96^\circ\text{C}/\text{W}$ when mounted on a minimum pad.

- 2: Pulse Test: Pulse Width < $300\mu\text{s}$, Duty cycle < 2.0%.
 3: Starting $T_J = 25^\circ\text{C}$, $L = 3\text{mH}$, $I_{AS} = 9\text{A}$, $V_{DD} = 100\text{V}$, $V_{GS} = 10\text{V}$.

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted.

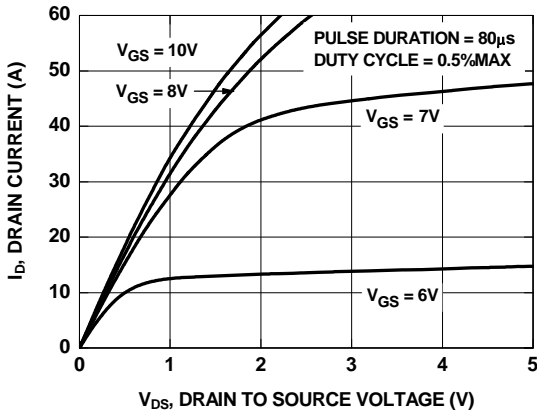


Figure 1. On-Region Characteristics

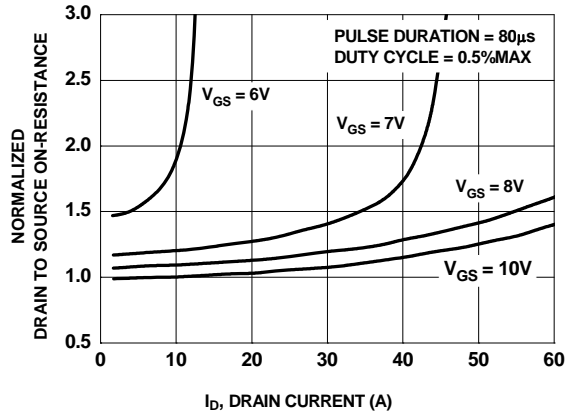


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

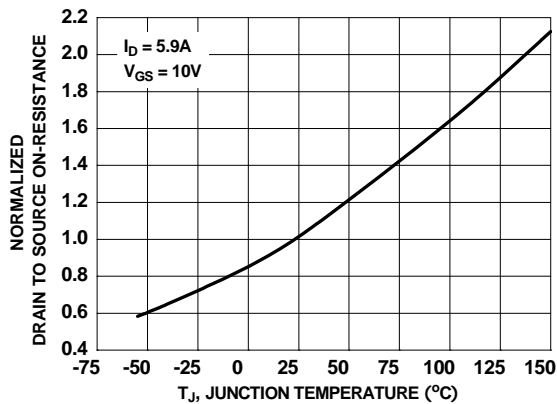


Figure 3. Normalized On-Resistance vs. Junction Temperature

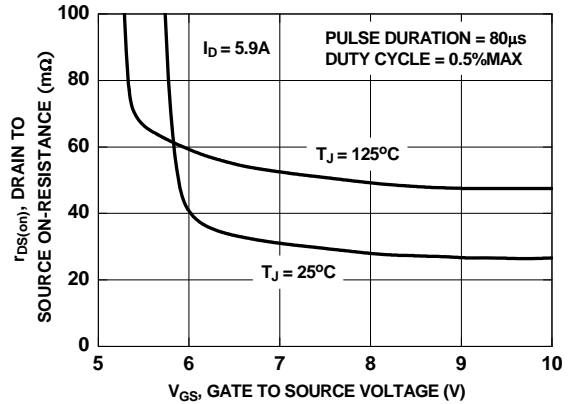


Figure 4. On-Resistance vs. Gate to Source Voltage

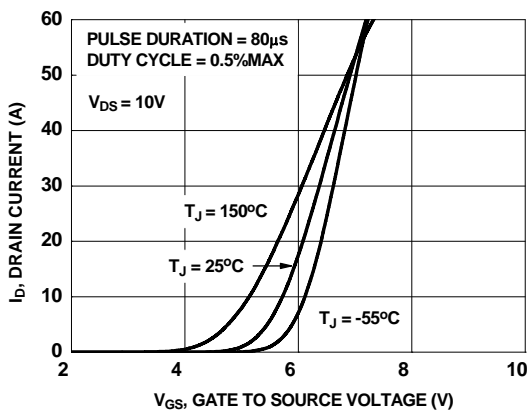


Figure 5. Transfer Characteristics

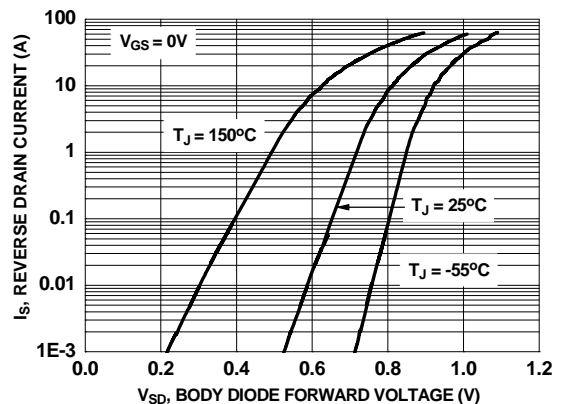


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted.

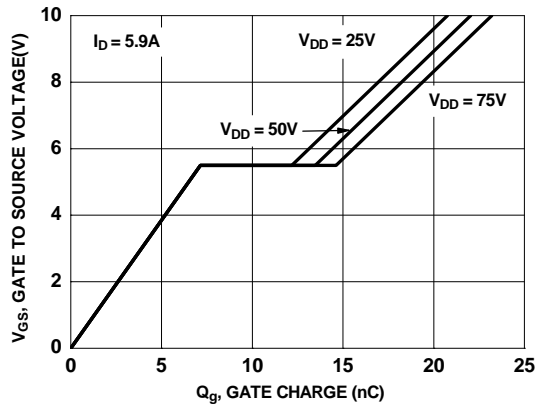


Figure 7. Gate Charge Characteristics

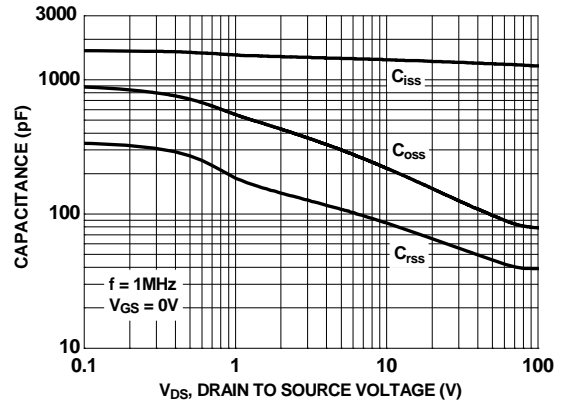


Figure 8. Capacitance vs. Drain to Source Voltage

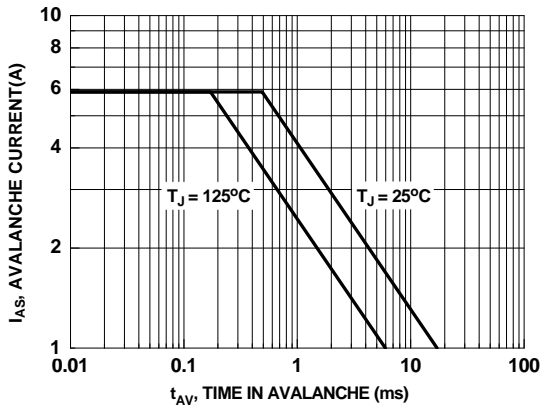


Figure 9. Unclamped Inductive Switching Capability

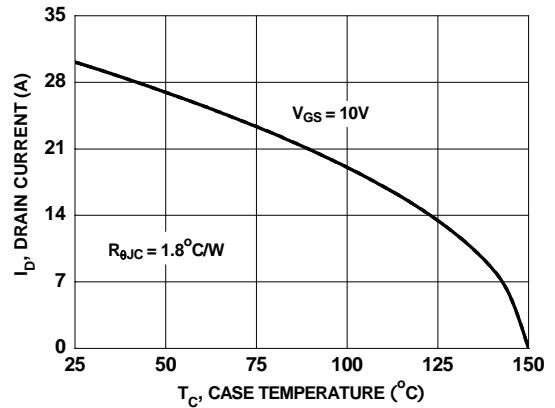


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

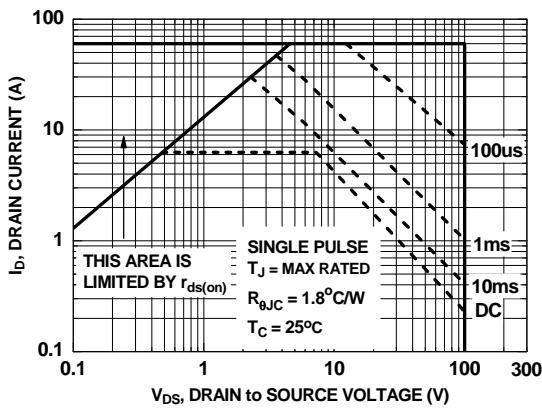


Figure 11. Forward Bias Safe Operating Area

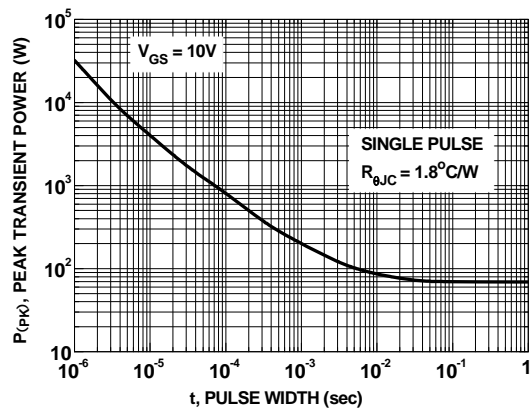
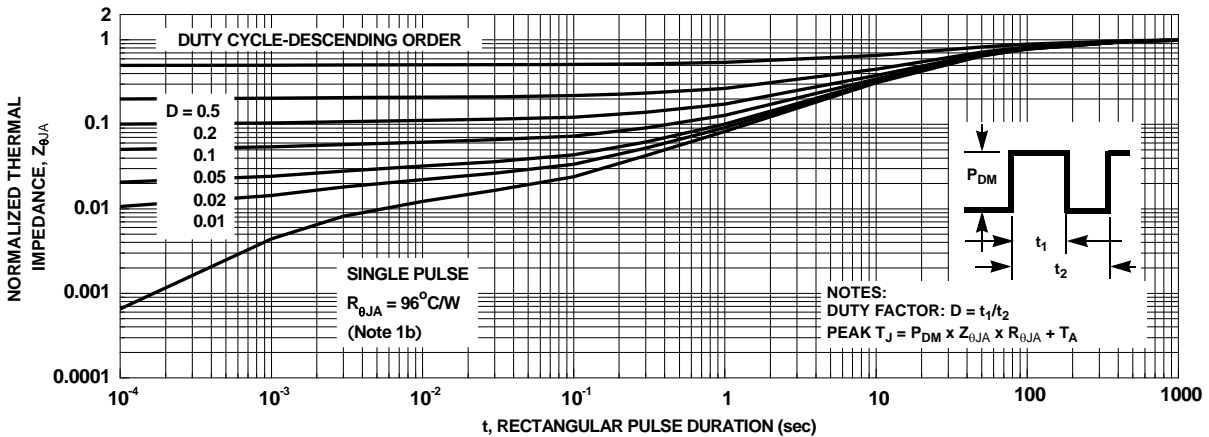
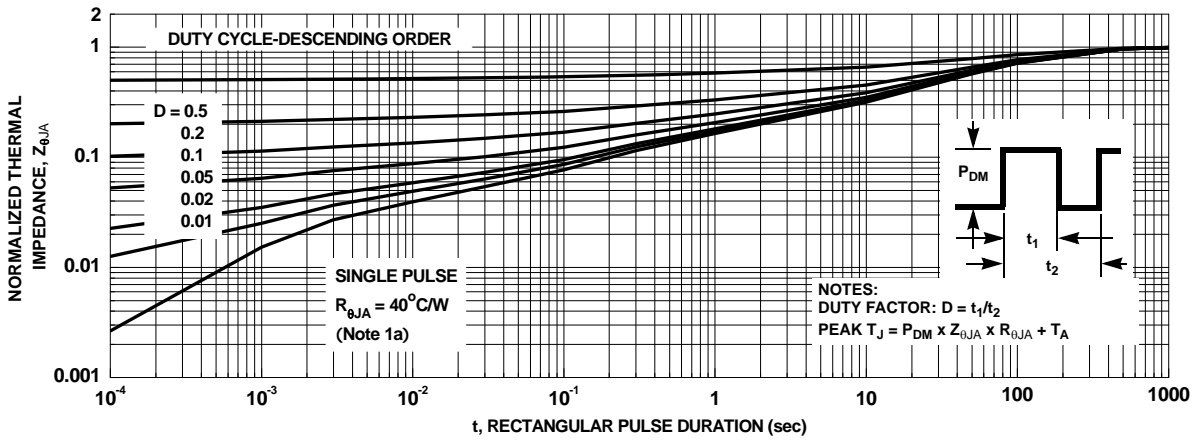
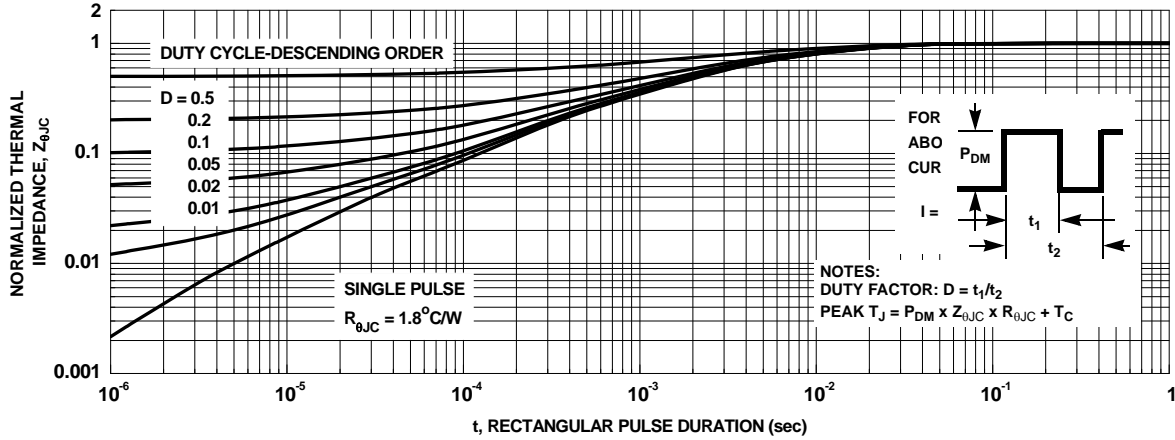


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted.



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